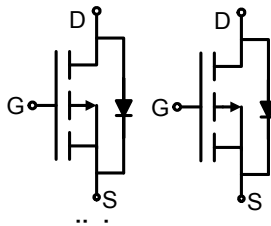
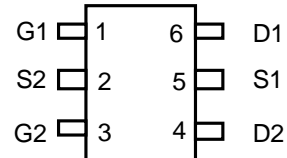
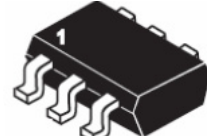


**Dual P-Channel Enhancement Mode Power MOSFET**

<p><b>DESCRIPTION</b></p> <p>The HM6803 uses advanced trench technology to provide excellent <math>R_{DS(ON)}</math>, low gate charge and operation with gate voltages as low as 2.5V. This device is suitable for use as a load switch or in PWM applications.</p> <p><b>GENERAL FEATURES</b></p> <ul style="list-style-type: none"> <li>● <math>V_{DS} = -20V, I_D = -3A</math></li> <li>● <math>R_{DS(ON)} &lt; 140m\Omega @ V_{GS} = -2.5V</math></li> <li>● <math>R_{DS(ON)} &lt; 110m\Omega @ V_{GS} = -4.5V</math></li> <li>● High Power and current handling capability</li> <li>● Lead free product is acquired</li> <li>● Surface Mount Package</li> </ul> <p><b>Application</b></p> <ul style="list-style-type: none"> <li>● PWM applications</li> <li>● Load switch</li> <li>● Power management</li> </ul>	<div style="text-align: center;">  <p><b>Schematic diagram</b></p> </div> <div style="text-align: center;">  <p><b>Marking and pin Assignment</b></p> </div> <div style="text-align: center;">  <p><b>SOT23-6L top view</b></p> </div>
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**Package Marking And Ordering Information**

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
6803	HM6803	SOT-23-6L	Ø180mm	8 mm	3000 units

**Absolute Maximum Ratings (TA=25°C unless otherwise noted)**

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	$V_{DS}$	-20	V
Gate-Source Voltage	$V_{GS}$	±12	V
Drain Current-Continuous	$I_D$	-3	A
Drain Current-Pulsed (Note 1)	$I_{DM}$	-10	A
Maximum Power Dissipation	$P_D$	1.2	W
Operating Junction and Storage Temperature Range	$T_J, T_{STG}$	-55 To 150	°C

**Thermal Characteristic**

Thermal Resistance, Junction-to-Ambient (Note 2)	$R_{\theta JA}$	104	°C/W
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**Electrical Characteristics (TA=25°C unless otherwise noted)**

Parameter	Symbol	Condition	Min	Typ	Max	Unit
<b>Off Characteristics</b>						
Drain-Source Breakdown Voltage	$BV_{DSS}$	$V_{GS} = 0V, I_D = -250\mu A$	-20	-24	-	V
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS} = -24V, V_{GS} = 0V$	-	-	-1	µA

Gate-Body Leakage Current	$I_{GSS}$	$V_{GS}=\pm 10V, V_{DS}=0V$	-	-	$\pm 100$	nA
<b>On Characteristics (Note 3)</b>						
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=-250\mu A$	-0.4	-0.7	-1	V
Drain-Source On-State Resistance	$R_{DS(ON)}$	$V_{GS}=-4.5V, I_D=-3A$	-	64	110	m $\Omega$
		$V_{GS}=-2.5V, I_D=-2A$	-	89	140	m $\Omega$

Forward Transconductance	$g_{FS}$	$V_{DS}=-5V, I_D=-2.8A$	-	9.5	-	S
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<b>Dynamic Characteristics (Note4)</b>						
Input Capacitance	$C_{iss}$	$V_{DS}=-10V, V_{GS}=0V,$ $F=1.0MHz$	-	950	-	PF
Output Capacitance	$C_{oss}$		-	115	-	PF
Reverse Transfer Capacitance	$C_{rss}$		-	75	-	PF

<b>Switching Characteristics (Note 4)</b>						
Turn-on Delay Time	$t_{d(on)}$	$V_{DD}=-10V, I_D=-1A$ $V_{GS}=-4.5V, R_{GEN}=10\Omega$	-	7	-	nS
Turn-on Rise Time	$t_r$		-	3	-	nS
Turn-Off Delay Time	$t_{d(off)}$		-	30	-	nS
Turn-Off Fall Time	$t_f$		-	12	-	nS
Total Gate Charge	$Q_g$	$V_{DS}=-10V, I_D=-3A,$ $V_{GS}=-2.5V$	-	9.5	-	nC
Gate-Source Charge	$Q_{gs}$		-	2	-	nC
Gate-Drain Charge	$Q_{gd}$		-	3	-	nC

<b>Drain-Source Diode Characteristics</b>						
Diode Forward Voltage (Note 3)	$V_{SD}$	$V_{GS}=0V, I_S=1.3A$	-	-	-1.2	V

**Notes:**

1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board,  $t \leq 10$  sec.
3. Pulse Test: Pulse Width  $\leq 300\mu s$ , Duty Cycle  $\leq 2\%$ .
4. Guaranteed by design, not subject to production

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS



Figure 1: Switching Test Circuit

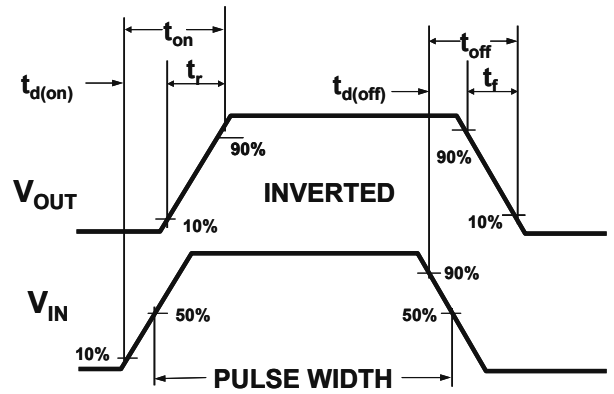


Figure 2: Switching Waveforms

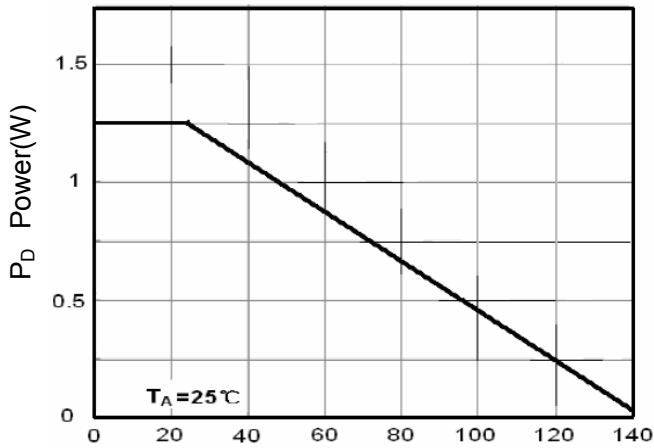


Figure 3 Power Dissipation

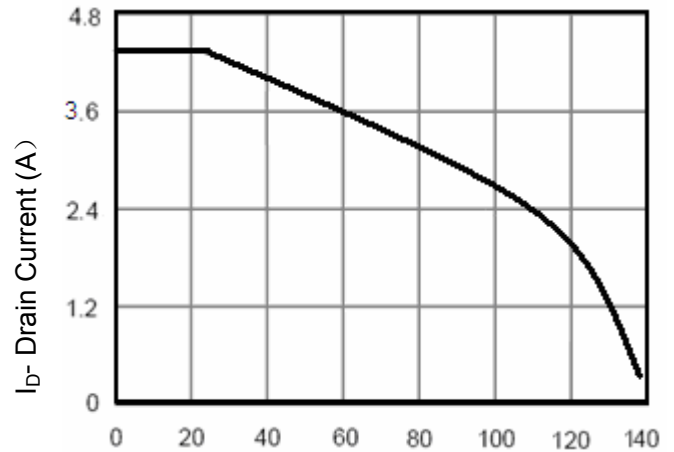


Figure 4 Drain Current

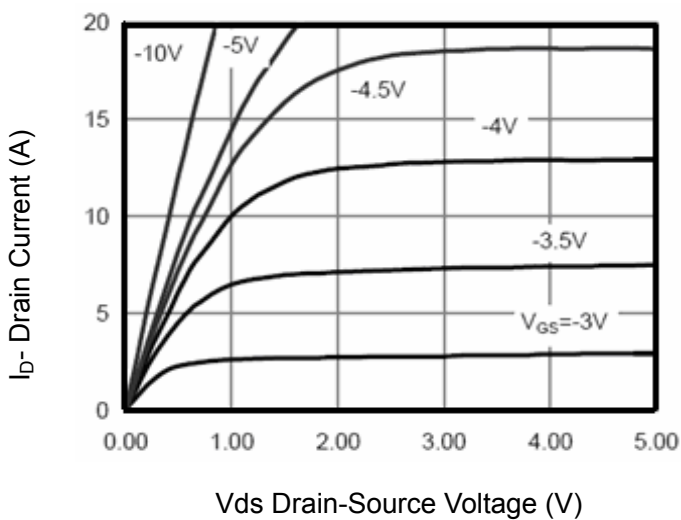


Figure 5 Output CHARACTERISTICS

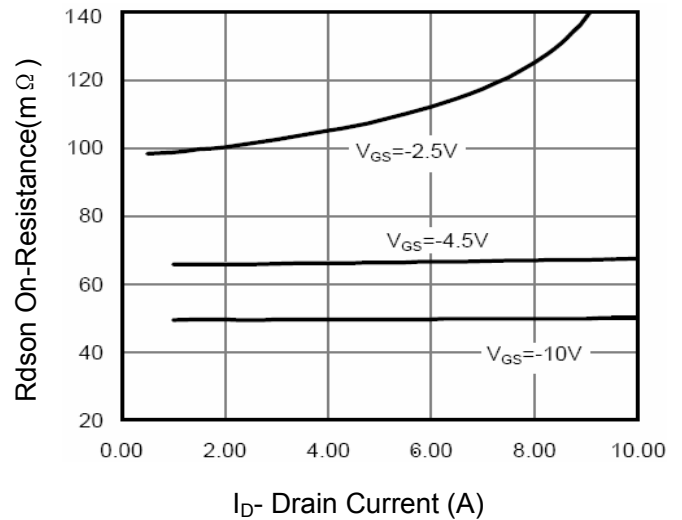


Figure 6 Drain-Source On-Resistance

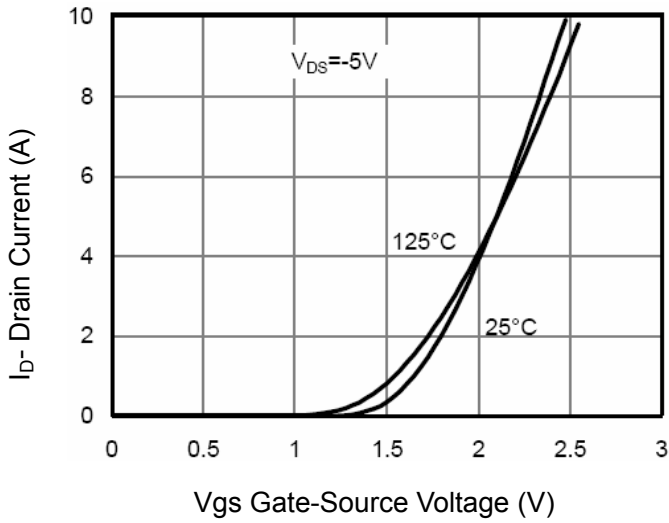


Figure 7 Transfer Characteristics

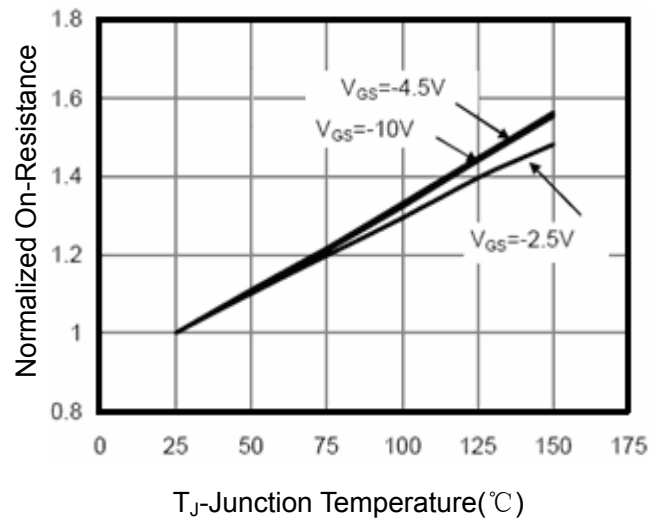


Figure 8 Drain-Source On-Resistance

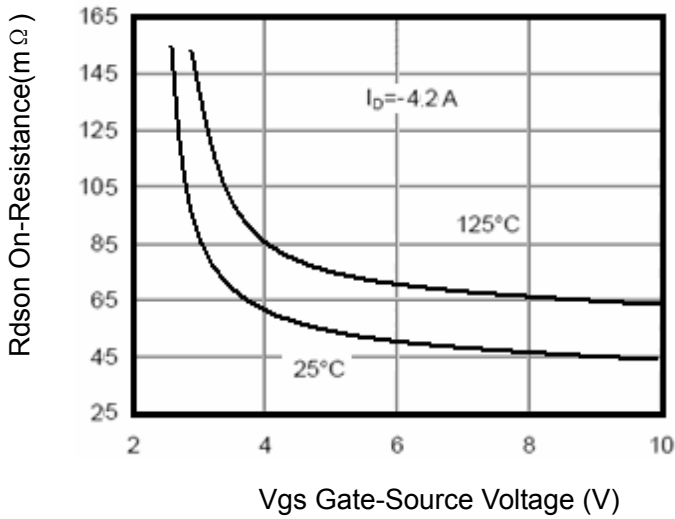


Figure 9 Rdson vs Vgs

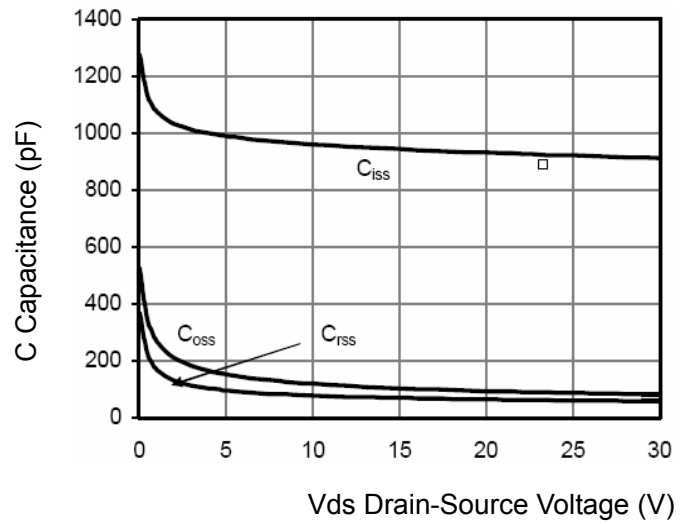


Figure 10 Capacitance vs Vds

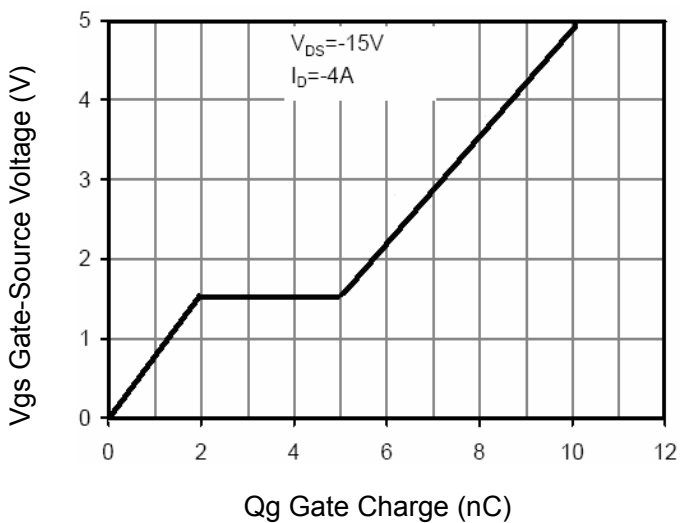


Figure 11 Gate Charge

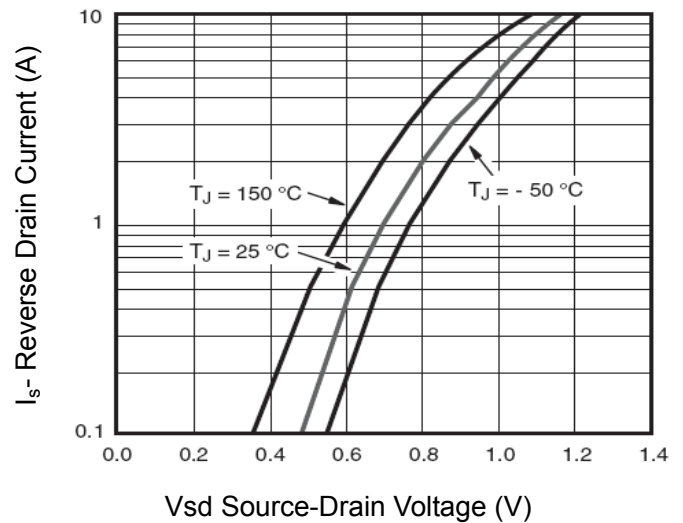


Figure 12 Source-Drain Diode Forward

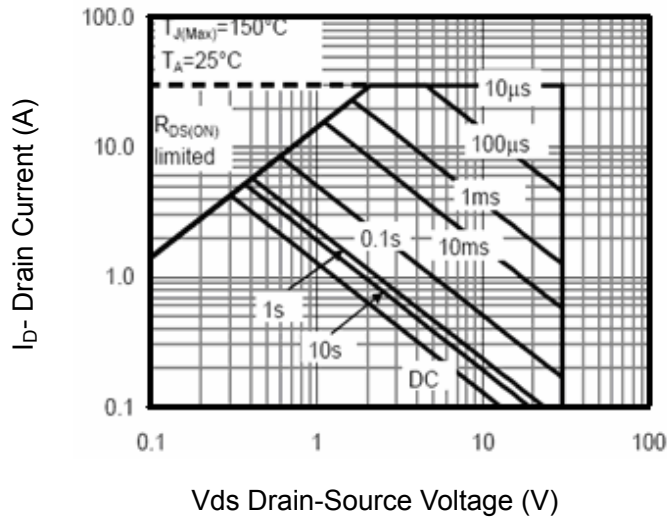


Figure 13 Safe Operation Area

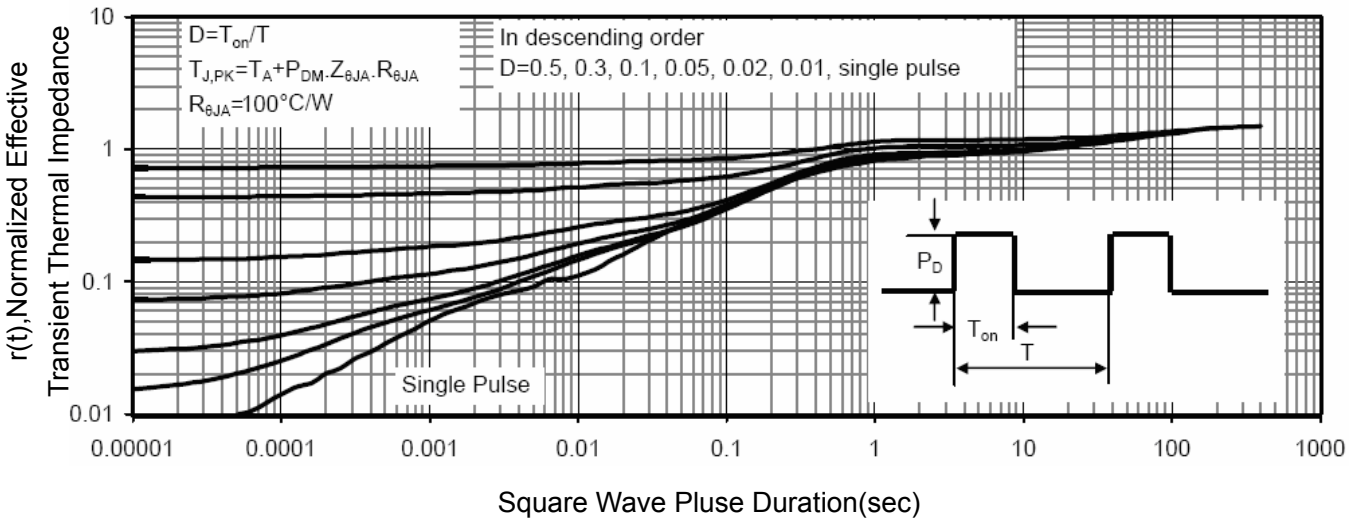
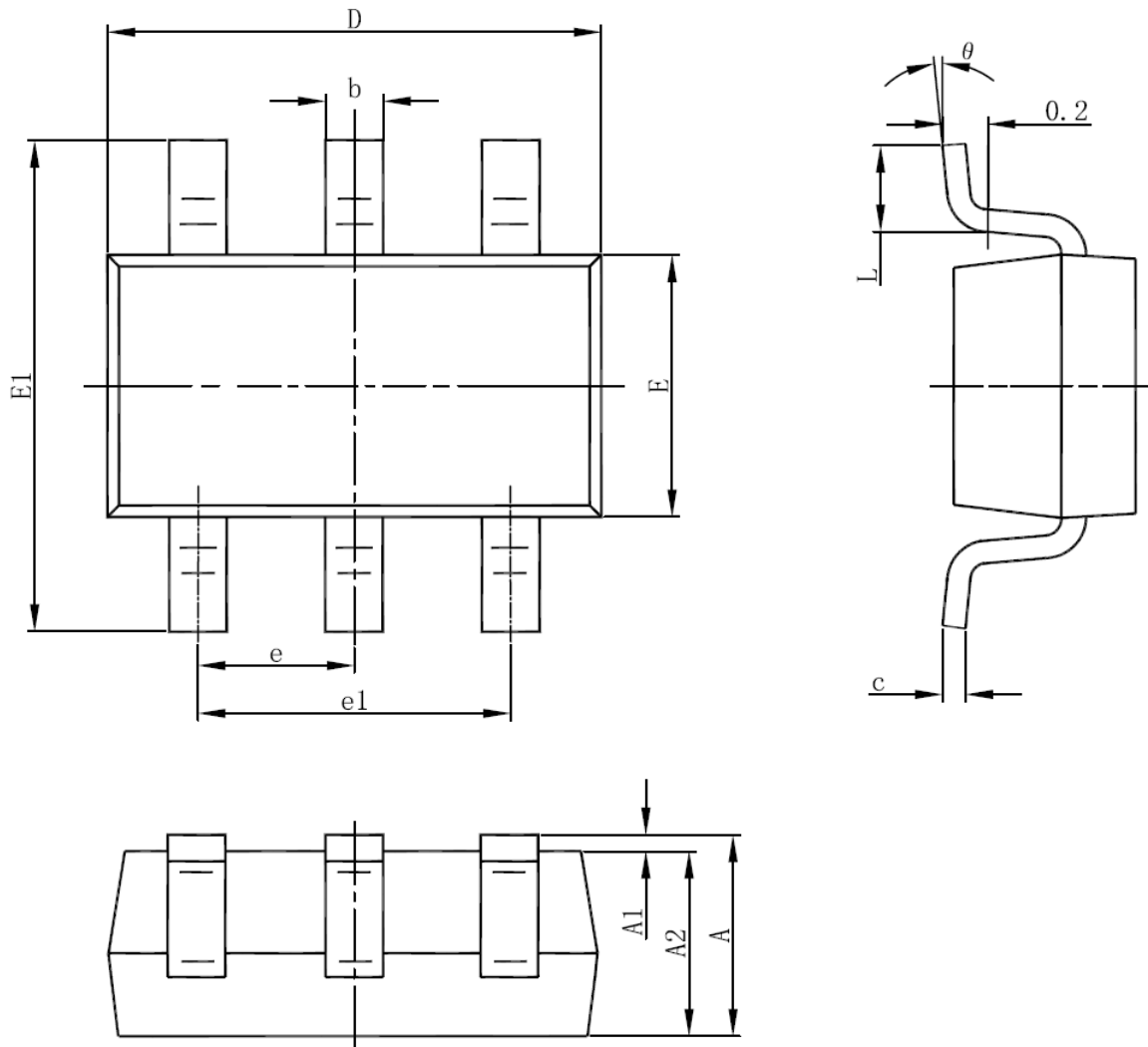


Figure 14 Normalized Maximum Transient Thermal Impedance

SOT-23-6L PACKAGE OUTLINE DIMENSIONS



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.050	1.250	0.041	0.049
A1	0.000	0.100	0.000	0.004
A2	1.050	1.150	0.041	0.045
b	0.300	0.500	0.012	0.020
c	0.100	0.200	0.004	0.008
D	2.820	3.020	0.111	0.119
E	1.500	1.700	0.059	0.067
E1	2.650	2.950	0.104	0.116
e	0.950(BSC)		0.037(BSC)	
e1	1.800	2.000	0.071	0.079
L	0.300	0.600	0.012	0.024
theta	0°	8°	0°	8°

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